

ABSTRACT

Provided is a substrate processing apparatus capable of improving processing uniformity of a substrate by bubbles of an inert gas formed in a processing liquid. A plurality of liquid supply pipes 31 and a plurality of bubble pipes 37 are disposed at bottom of a processing tank 18. In the liquid supply pipes 31, liquid discharge holes 31a and 31b for discharging the processing liquid downward inward and downward outward are formed. In the bubble pipes 37, gas discharge holes 37a for discharging nitrogen gas downward inward are formed. Each of the bubble pipes 37 is divided into a first discharge unit 41 and a second discharge unit 42 by a partition plate 40 at substantially the center of arrangement range of substrates 11. The first discharge unit 41 and the second discharge unit 42 of each bubble pipe 37 are supplied with the nitrogen gas whose flow rate is independently adjusted by a flow rate adjustment unit 52 respectively connected to the discharge units.